



SDMP0340LT /LST /LCT /LAT

SURFACE MOUNT SCHOTTKY BARRIER DIODE

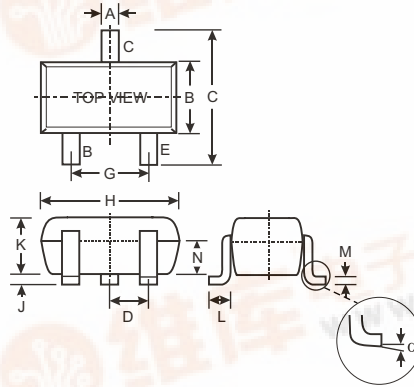
NEW PRODUCT

Features

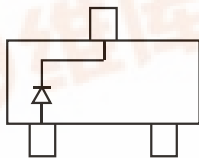
- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideal for low logic level applications
- Low Capacitance

Mechanical Data

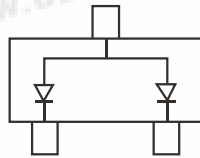
- Case: SOT-523, Molded Plastic
- Case Material UL Flammability Rating: 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: See Diagrams Below
- Marking: See Diagrams Below & Page 3
- Weight: 0.002 grams (approx.)
- Ordering Information, see Page 3



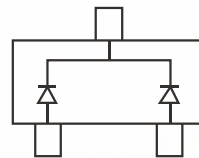
SOT-523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—
All Dimensions in mm			



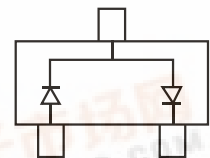
SDMP0340LT Marking: SM



SDMP0340LAT Marking: SQ



SDMP0340LCT Marking: SP



SDMP0340LST Marking: SN

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	40	V
RMS Reverse Voltage	$V_{R(RMS)}$	28	V
Forward Continuous Current (Note 1)	I_{FM}	30	mA
Non-Repetitive Peak Forward Surge Current @ 8.3ms Single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	200	mA
Power Dissipation (Note 1)	P_d	150	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	833	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{STG}	-40 to +125	$^\circ\text{C}$

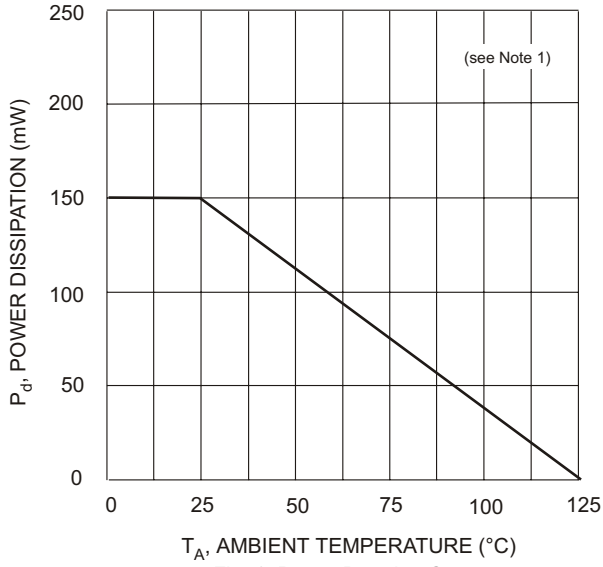
Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	$V_{(BR)R}$	40	—	—	V	$I_R = 10\mu\text{A}$
Forward Voltage Drop (Note 2)	V_F	—	290	370	mV	$I_F = 1\text{mA}$
Leakage Current (Note 2)	I_R	—	—	1.0	μA	$V_R = 10\text{V}$
Total Capacitance	C_T	—	2	—	pF	$V_R = 1\text{V}, f = 1.0\text{MHz}$

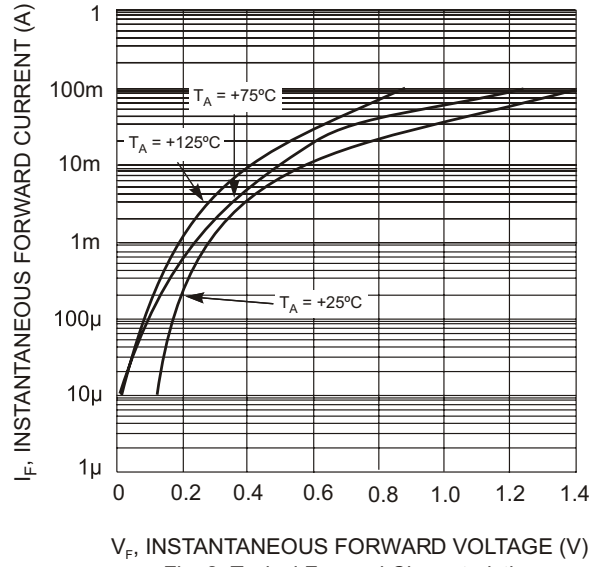
Notes: 1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

2. Short duration test pulse used to minimize self-heating effect.

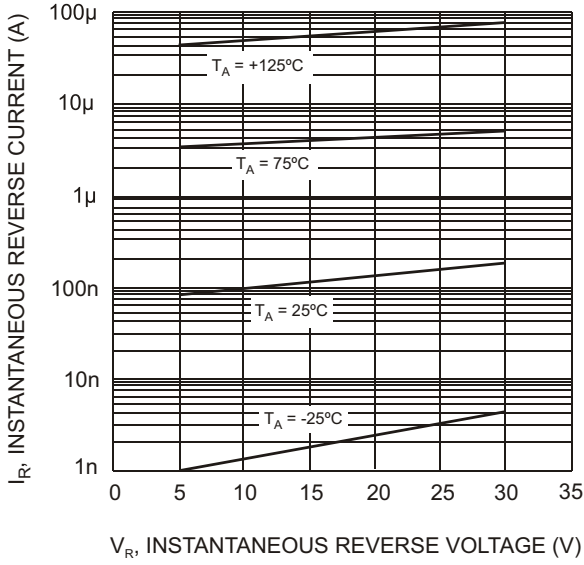




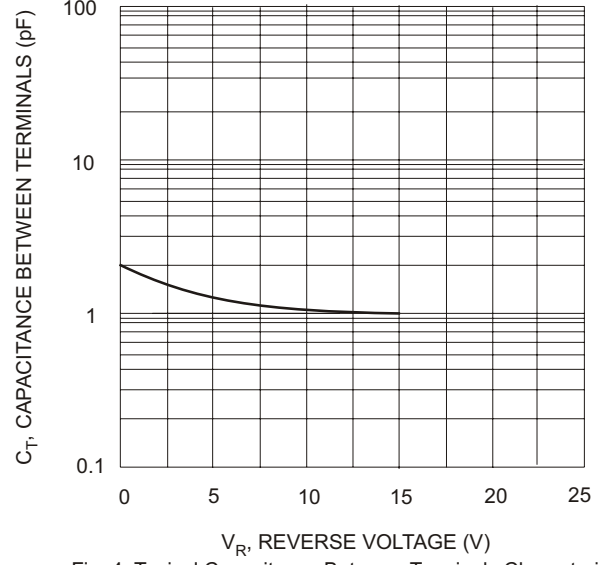
T_A , AMBIENT TEMPERATURE (°C)
Fig. 1, Power Derating Curve



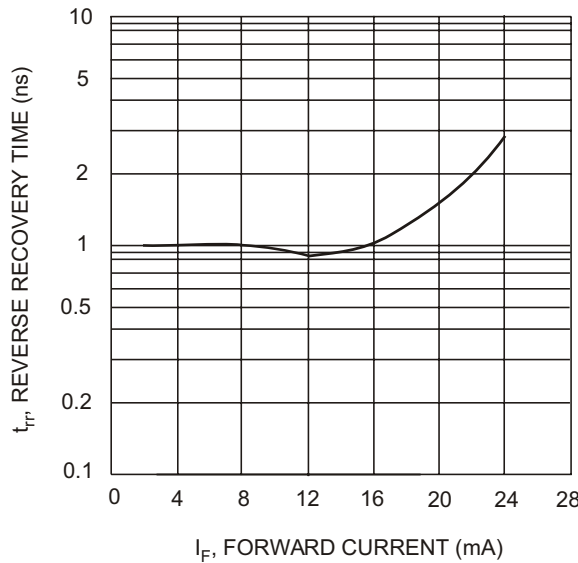
V_F , INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 2 Typical Forward Characteristics



V_R , INSTANTANEOUS REVERSE VOLTAGE (V)
Fig. 3 Typical Reverse Characteristics



V_R , REVERSE VOLTAGE (V)
Fig. 4 Typical Capacitance Between Terminals Characteristics



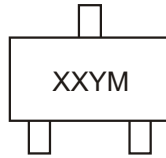
I_F , FORWARD CURRENT (mA)
Fig. 5 Typical Reverse Recovery Time Characteristics

Ordering Information (Note 3)

Device	Packaging	Shipping
SDMP0340LT-7	SOT-523	3000/Tape & Reel
SDMP0340LST-7	SOT-523	3000/Tape & Reel
SDMP0340LCT-7	SOT-523	3000/Tape & Reel
SDMP0340LAT-7	SOT-523	3000/Tape & Reel

Notes: 3. For Packaging Details: go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



XX = Product Type Marking Code (See Page 1)
 YM = Date Code Marking
 Y = Year (ex: N = 2002)
 M = Month (ex: 9 = September)

Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009
Code	M	N	P	R	S	T	U	V	W

Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D